

PROHIBITED MATERIALS PLATING RESTRICTIONS

1.0 Definition of terms:

1.01 The term “shall”, “will” and “may” are used with specific intent thought-out these documents and will observe the following rules:

- 1.1** Requirements defined using “**shall**” in the text are mandatory requirements and are considered to be binding and require formal verification. Departure from such a requirement is not permissible without formal agreement between Subcontractor and CSPI.
- 1.2** Requirements defined using “**will**” in the text expresses a provision or service by CSPI or an intention by CSPI in connection with a requirement of this document. The subcontractor is implicitly authorized to rely on such service or intention.
- 1.3** The word “**may**” in the text expresses a permissible practice or action. It does not express a requirement of this document.

2.0 Prohibited Materials Plating Restrictions

2.0.1 The uses of Pure Tin Plated finishes are strictly PROHIBITED. Any Tin Plating or Tin Solder processes **shall contain NO LESS than 3 percent LEAD composition**, unless specifically authorized in writing by the CSP Inc. These restrictions apply for all types and levels of procurements, with the supplier responsible for communicating these restrictions to subcontractors or sub-tier suppliers as required.

2.1 EXEMPTION: If a CSP Inc. Technical Data Package (CSP Inc. Drawing or Military Specification) referenced on this order specifies the use of pure tin finishes this prohibition is NOT applicable. Designs and/or parts previously approved by CSP Inc. on the initial production of the Signal Processor do not have to be approved again.

2.2 NOTE: If the CSP Inc. Technical Data Package specifies a Seller Part Number which contains pure tin, then the purchase order or CSP Inc. Technical Data Package must specifically authorize the use of pure tin for the specified part number(s).

2.3 NOTE: Tin -plated finishes may be used if: (a) the seller has a written tin control plan in accordance with GEIA-STD-0005-2 that has been approved in writing by CSP Inc., and (b) the tin usage conforms with requirements of the plan.
Lead-free solder processes may be used if: (a) the seller has a written Lead-Free control plan in accordance with GEIA-STD-0005-1 that has been approved in writing by CSP Inc., and (b) the lead-free solder usage conforms to the requirements of the plan.

This document is an integral part of the purchase order. The revision in effect at the time the purchase order was placed applies.